



# SOT1762-1

SSOP32, plastic, shrink small outline package; 32 terminals;  
0.65 mm pitch; 7.5 mm x 11 mm x 2.5 mm body

28 September 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SSOP32
<b>Package type industry code</b>	SSOP32
<b>Package style descriptive code</b>	SSOP (shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	29-02-2016
<b>Manufacturer package code</b>	98ARH99137A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	11	-	mm
package width	-	7.5	-	mm
package height	-	2.5	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	32	-	



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2 Package outline

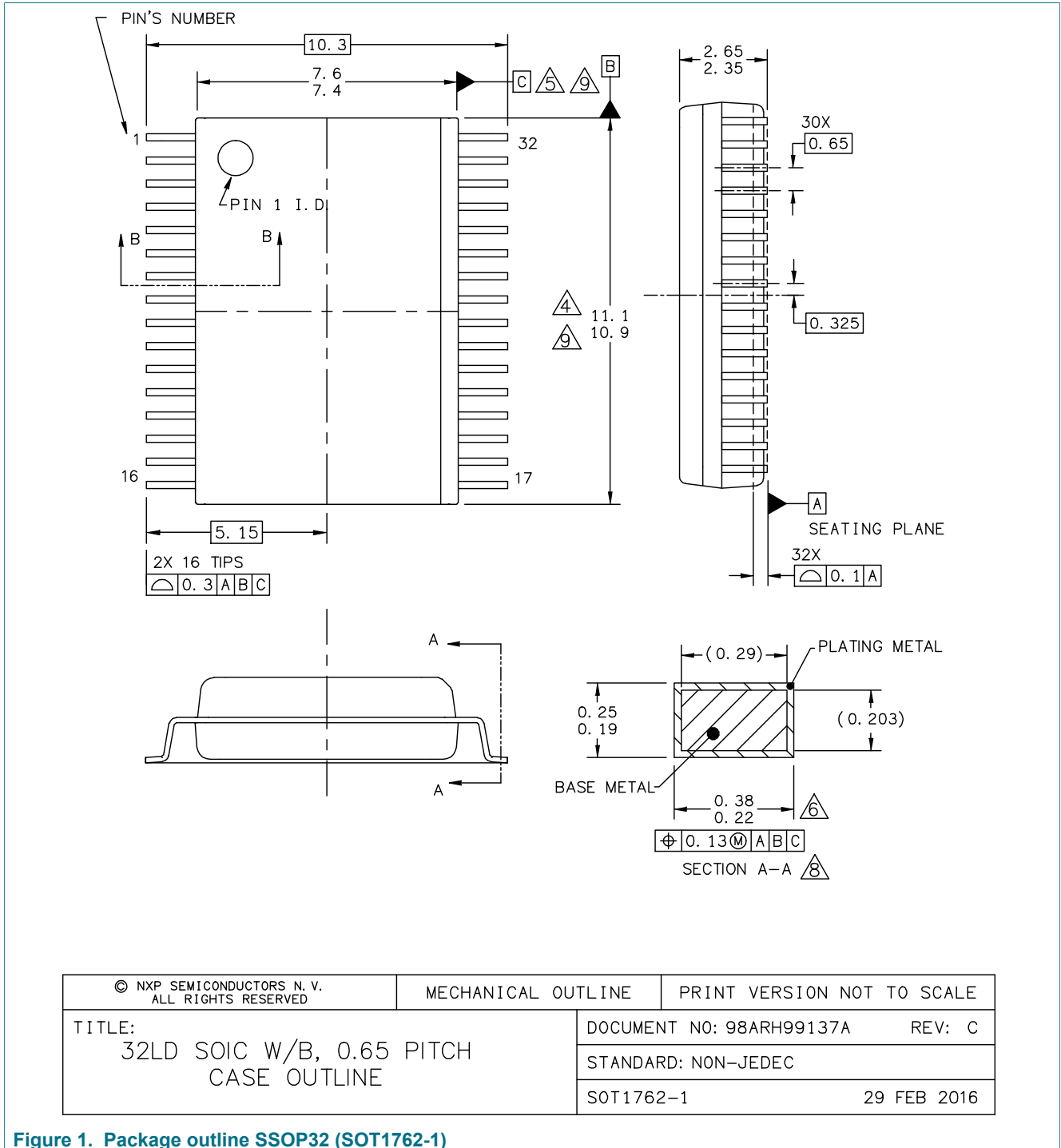


Figure 1. Package outline SSOP32 (SOT1762-1)

SSOP32, plastic, shrink small outline package; 32 terminals; 0.65 mm pitch; 7.5 mm x 11 mm x 2.5 mm body

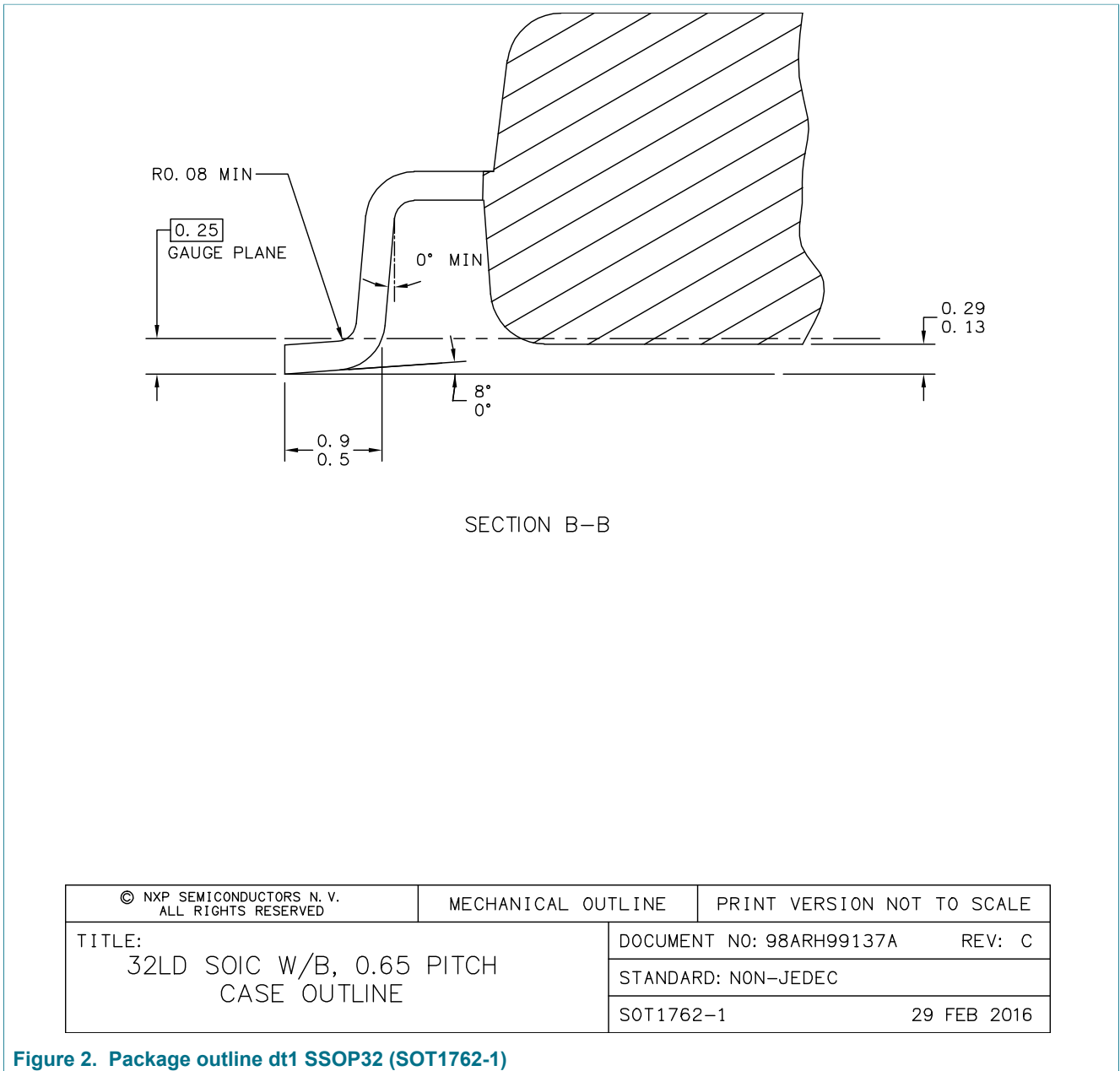


Figure 2. Package outline dt1 SSOP32 (SOT1762-1)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
  2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
  3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
- △4 THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
  - △5 THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
  - △6 THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.4 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT LESS THAN 0.07 mm.
  - △7 EXACT SHAPE OF EACH CORNER IS OPTIONAL.
  - △8 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.3 mm FROM THE LEAD TIP.
  - △9 THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 32LD SOIC W/B, 0.65 PITCH CASE OUTLINE	DOCUMENT NO: 98ARH99137A	REV: C
	STANDARD: NON-JEDEC	
	SOT1762-1	29 FEB 2016

Figure 3. Package outline note SSOP32 (SOT1762-1)

### 3 Legal information

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body

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